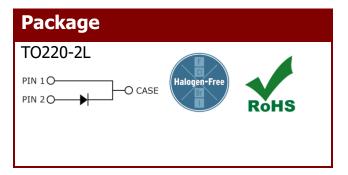


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1200V, 50A Homogeneous-current SiC Schottky diode

Description

Homogeneous-current SiC Schottky diode with low V_F , high repetitive surge current, low leakage, no reverse or forward recovery, and high-temperature operation.



Features

- Temperature-independent fast switching
- Low reverse leakage current
- Low V_F at high temperatures
- Easy paralleling (positive temperature coefficient of V_F)
- Essentially no switching losses
- Subject to AEC-Q101 qualification
- High repetitive surge current

Typical applications

- High-frequency power converters
- Industrial motor drives
- Switch-mode power supplies
- Electric vehicles and battery chargers
- Solar inverters
- Power factor correction
- Free-wheeling diode

Maximum ratings

Parameter	Symbol	Test conditions	Value	Unit	Note
Repetitive peak reverse voltage	V_{RRM}		1200	V	
DC peak reverse voltage	V_R		1200	V	
		<i>T</i> _C =25°C	149		
Continuous forward current	I_{\digamma}	$T_C = 135$ °C	72	Α	Fig. 3
		T_C =150°C	53		
Power dissipation	P_{TOT}	T_C =25°C	682	W	Fig. 4
		T_C =110°C	295		
Repetitive peak forward surge	I_{FRM}	T_C =25°C, t_P =10ms,	210	Α	Fig. 5
current, which limits the chip		half sine pulse			
temperature to 175°C					
Non-repetitive forward square-	I _{F,MAX}	<i>T_C</i> =25°C, <i>t_P</i> =10μs	963	Α	
pulse surge current		<i>T_C</i> =115°C, <i>t_P</i> =10μs	871	Α	
Operating junction and storage	T_j , T_{stg}		-55 to	°C	
temperature			175		





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Electrical characteristics

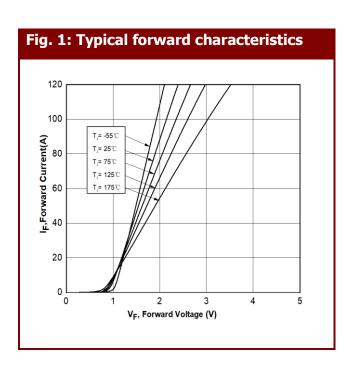
Parameter	Symbol	Тур.	Max.	Unit	Test conditions	Note
Forward voltage	V_F	1.5	1.7	V	<i>I_F</i> =50 A <i>T_j</i> =25°C	Fig. 1
		1.9			<i>I_F</i> =50 A <i>T_j</i> =175°C	
Reverse current	I_R	10	40	μΑ	<i>V_R</i> =1200 V <i>T_j</i> =25°C	Fig. 2
		70			<i>V</i> _R =1200 V	
					<i>T_J</i> =175°C	
Reverse recovery	Q_{rr}	0		nC	Note: Majority-carrie	r diode
charge						
		2,380			<i>V</i> _R =0 V, <i>f</i> =1 MHz	
Total capacitance	С	186		nF	<i>V</i> _R =400 V, <i>f</i> =1 MHz	Fig. 6
		181			<i>V</i> _R =800 V, <i>f</i> =1 MHz	
Total capacitive charge	Q c	206		nC	<i>V</i> _R =800 V, <i>T</i> _J =25°C	Fig. 7
Capacitance stored	E _C	51		μJ	<i>V</i> _R =800 V	Fig. 8
energy				-		

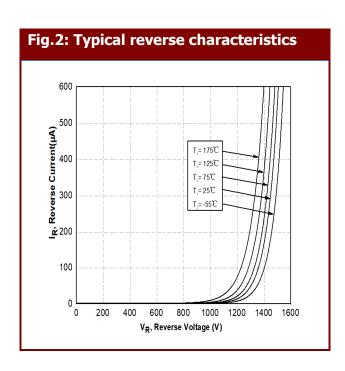
Thermal characteristics

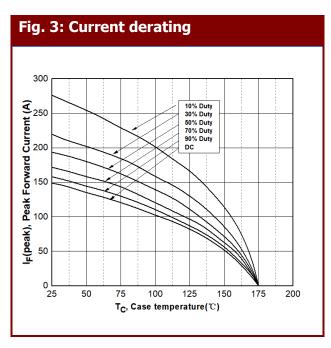
Parameter	Symbol	Typ.	Unit	Note
Thermal resistance from junction to case	$R_{\!\scriptscriptstyle extsf{ heta}\!J\!C}$	0.22	°C/W	Fig. 9

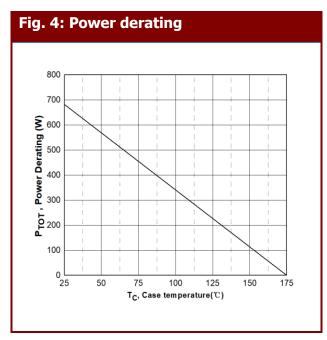


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Fig. 5: Chip temperature during repetitive peak forward surge currents

[ref.: J. Damcevska, S. Dimitrijev, D. Haasmann, and P. Tanner, *Scientific Reports*, 13:19189, 2023; https://doi.org/10.1038/s41598-023-465 38-6]

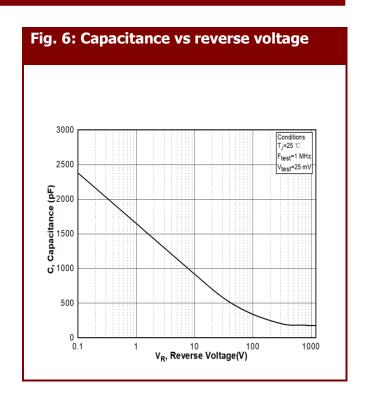
6

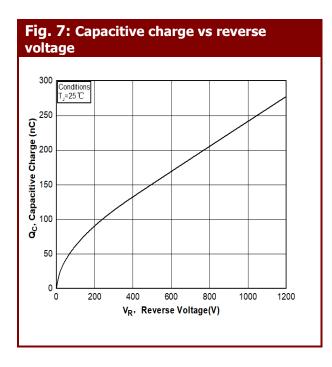
Time during a half sine pulse (ms)

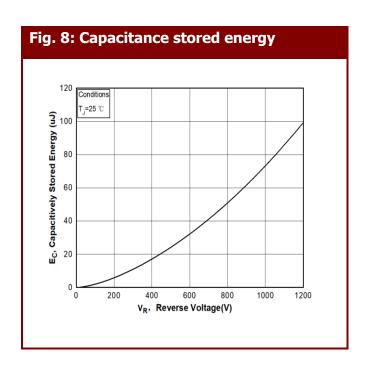
10

75 50

25

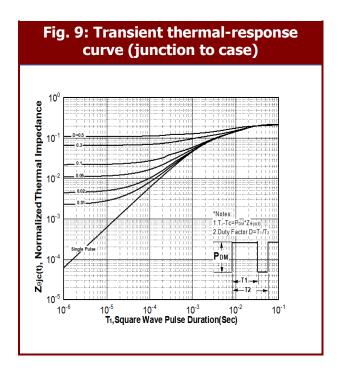








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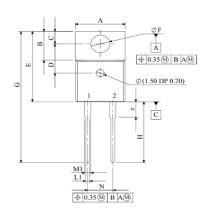


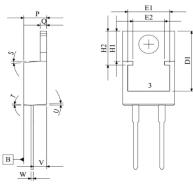


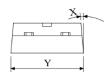
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Package Dimensions

Package TO-220-2L

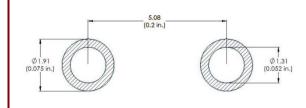






SYMBOL	MIN (mm)	MAX (mm)	
A	9.677	10.414	
В	5.969	6.477	
C	2.540	3.048	
D	5.664	8.560	
D1	12.450 REF		
E	14.986	15.621	
E1	8.120	REF	
E2	6.100 REF		
F	3.632	3.886	
G	28.067	29.134	
H	12.700	13.970	
H1	6.223 REF		
H2	7.040	REF	
L1	0.635	0.914	
M1	1.143	1.397	
N	4.953	5.207	
P	4.191	4.699	
Q	1.219	1.372	
S	3°	6°	
T	3°	6°	
U	3°	6°	
V	2.388	2.794	
W	0.356	0.635	
W 1	0.356	0.520	
X	3°	5.5 °	
Y	9.779	10.414	
Z	3.302	3.810	

Recommended Solder Pad Layout



Part Number	Package	Marking
QSD50HCS120U	TO-220-2L	Q

TO-220-2L